

L Number	Hits	Search Text	DB	Time stamp
9	3	heat with radiation same chip and bump and resist adj assist adj bonding	USPAT; US-PGPUB; EPO; JPO	2004/04/18 15:10
10	444	heat with radiation same chip and bump and bonding	USPAT; US-PGPUB; EPO; JPO	2004/04/18 15:12
11	100	ceramic with substrate same second with cavity	USPAT	2004/04/18 15:15
12	23	ceramic with substrate same second with cavity and second with chip	USPAT	2004/04/18 15:15